

CHASM Advanced Materials Preferred Integration Partner Program

The CHASM Preferred Integration Partner Program (PIP) is designed to incentivize and reward select business partners for CHA SM products with the goal of driving revenue growth and market penetration mutually for both organizations. CHASM products offer an innovative and novel platform to both land new clients a s well as upsell existing clients for PIP members eager to strategically engage with both CHASM and the marketplace.

Membership Application

Membership in the CHASM PIP Program is offered exclusively to companies not just having an established customer base for flexible printed electronics but also those demonstrating leading expertise at integrating flexible printed electronics into finished product or electronic assemblies. PIP member companies represent the "go-to companies" in the industry, offering their customers extensive integration capabilities and consultative expertise on the latest innovations in the industry.

In order to apply for membership in the CHASM PIP Program, please email the completed form to partners@chasmtek.com. You'll be contacted within one business day to confirm receipt and for any additional information as required.

Company

Please provide details about your company.

Company Name:	
Street Address:	
City:	
State or Province:	
Zip:	
Country:	
Website:	
Date Established:	
Number of Employees:	
Territory:	
No. of Customers:	
Industries Served:	



Please provide detai	ls of the designated co	ontact	from your company:			
Title: Office	ct Name: Phone: Phone:					
Please explain your	existing customer bas	se for f	lexible printed electronics	5:		
Click or tap here to e	enter text.					
Please describe the	flexible printed electi	ronics r	materials currently in use	at your company:		
Click or tap here to e	enter text.					
Please describe any	active projects requi	ring Ag	eNT transparent conduct	films:		
Click or tap here to e	enter text.					
Please list all of you	r company's existing	partne	rs:			
Click or tap here to e	enter text.					
Competencies P	Profile					
Please select all that	apply.					
	Production Capabilities					
	Circuit Design:		OCA:			
	Screen Printing:		Laminating:			
	Wet Etch:		Component Assembly:			
	Laser Ablation:		Inline Test:			
	Laser Cutting:		QA/QC:			
	Die Cut/Punch:		Contacts/Busbar:			



Application Expertise

		Produce	Engineer	
	Touch Screens:			
	Touch Sensors/Buttons:			
	Flexible Displays:			
	Sensors:			
	Heaters:			
	Antennas:			
	In-mold Electronics:			
	Transparent Wiring:			
Signature:				
Printed Nan	ne:			
Position:				_
Date:				

Signature